

CROSS-REFERENCE TO RELATED APPLICATION(S)


[0001]

A1 The present application is a continuation-in-part of U.S. Application No. 09/651,779, filed August 30, 2000 and entitled "Methods and Apparatus for Removing Conductive Material from a Microelectronic Substrate;" U.S. Application No. 09/888,084, filed June 21, 2001, and entitled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material from a Microelectronic Substrate;" and U.S. Application No. 09/887,767, filed June 21, 2001, and entitled "Microelectronic Substrate Having Conductive Material With Blunt-Cornered Apparatus, and Associated Methods for Removing Conductive Material;" all of which are herein incorporated in their entirety by reference.

REMARKS

Applicants respectfully request consideration of the application in view of this preliminary amendment. If the Examiner has any questions or matters that can be expediently handled by telephone, he or she is encouraged to contact Mr. Parker, attorney for the Applicants.

Respectfully submitted,
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